Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
⌘	1	39.76mil (1.010mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r430_170h101_356r85			
A	2	29.92mil (0.760mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r380_150h76_305r75			
□	2	40.16mil (1.020mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn102			
✿	2	50.00mil (1.270mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c127hn127			
O	2	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c222h160			
⌘	2	96.46mil (2.450mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c200hn245			
⌘	2	105.91mil (2.690mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c-127hn269			
O	2	125.98mil (3.200mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c320hn320m320p0			
⊕	4	118.11mil (3.000mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c300hn300m315			
V	5	28.00mil (0.71mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c104h71			
B	6	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
✖	20	15.00mil (0.38mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c64h38m0mx0			
D	32	25.00mil (0.635mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c104h64m104mx0			
⊠	32	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
✱	48	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c68h40m0mx0			
⊕	52	66.93mil (1.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c260h170m260p0			
◇	54	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
C	58	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
V	59	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)			
F	148	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v61h30m0mx0			
E	1990	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)	Rounded	(Mixed)			
	2543 Total										

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1	Megtron6	5.70mil	3.23	
2	L2 GND	CF-004	1.40mil		
	Dielectric 3	FR4-370HR	3.00mil	3.72	
3	L3 PWR	CF-004	2.76mil		
	Dielectric 5	FR4-370HR	3.00mil	3.86	
4	L4 GND	CF-004	1.40mil		
	Dielectric 7	FR4-370HR	3.00mil	3.72	
5	L5 PWR/SIG	CF-004	1.38mil		
	Dielectric 11	FR4-370HR	3.00mil	3.86	
6	L6 GND	CF-004	1.38mil		
	Dielectric 15	FR4-370HR	4.80mil	3.92	
7	L7 SIGNAL	CF-004	0.69mil		
	Dielectric 9	FR4-370HR	4.80mil	3.92	
8	L8 GND	CF-004	1.38mil		
	Dielectric 13	FR4-370HR	4.80mil	3.92	
9	L9 GND	CF-004	1.38mil		
	Dielectric1	FR4-370HR	4.80mil	3.92	
10	L10 SIGNAL	CF-004	1.38mil		
	Dielectric 14	FR4-370HR	4.80mil	3.92	
11	L11 GND	CF-004	1.38mil		
	Dielectric 10	FR4-370HR	4.80mil	3.92	
12	L12 SIGNAL	CF-004	0.69mil		
	Dielectric 16	FR4-370HR	4.80mil	3.92	
13	L13 GND	CF-004	1.38mil		
	Dielectric 12	FR4-370HR	3.00mil	3.86	
14	L14 PWR	CF-004	1.38mil		
	Dielectric 8	FR4-370HR	3.00mil	3.72	
15	L15 GND	CF-004	1.40mil		
	Dielectric 6	FR4-370HR	3.00mil	3.86	
16	L16 PWR/SIG	CF-004	2.76mil		
	Dielectric 4	FR4-370HR	3.00mil	3.72	
17	L16 GND	CF-004	1.40mil		
	Dielectric 2	Megtron6	5.70mil	3.23	
18	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Total board thickness: 96.11mil

M10 Fab Notes

DESIGN INFORMATION

MIN. TRACK WIDTH: 3.5 MIL
MIN. CLEARANCE: 4 MIL
MIN. VIA PAD SIZE: 20 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] **HYBRID STACKUP** [ ] **UNIFORM STACKUP**
[X] ISOLA FR4-370HR
[ ] Megtron 4 **OR** Isola I-Speed
[X] Megtron6 **OR** Isola MT-40 **OR** Nelco MW-1000
[ ] OTHER _____

THICKNESS: [ ] 62 MIL (1.6mm) +/-10% [X] OTHER 96 MIL +/-10%
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER DARK GREEN
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] HARD GOLD (30u)
[ ] OTHER _____

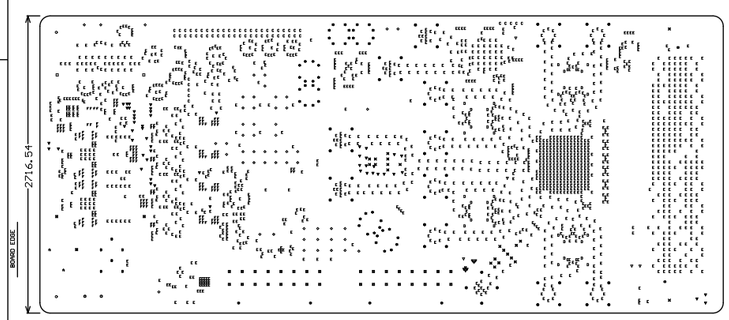
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

[X] 16 MIL & SMALLER VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[X] OUTER LAYER TRACKS 12.1 MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[X] OUTER LAYER TRACKS 7.4 MIL WIDE WITH 5 MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE
[ ] INNER LAYERS TRACKS XX MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[X] INNER LAYER TRACKS 3.5 MIL WIDE WITH 6.5 MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE



1000.00mil

TEXAS INSTRUMENTS

PROJECT TITLE: ADC34RF7xEVM
DESIGNED FOR: Not For Public Release
FILE NAME: ADC34RF7x_REV_A.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: -	REV: A	SVN REV: cfec0883921a2ab84ee9ab1a05e8e2aa5b45f222 [Locally Modified]
LAYER NAME = [redacted]			
PLOT NAME = Fabrication Drawing	GENERATED : 3/13/2025 2:19:06 PM	TEXAS INSTRUMENTS	

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ENGINEER: CW	LAYOUT BY: CW/GR
SCALE: 1.00	ALTIUM DESIGNER VERSION: 24.7.2.38